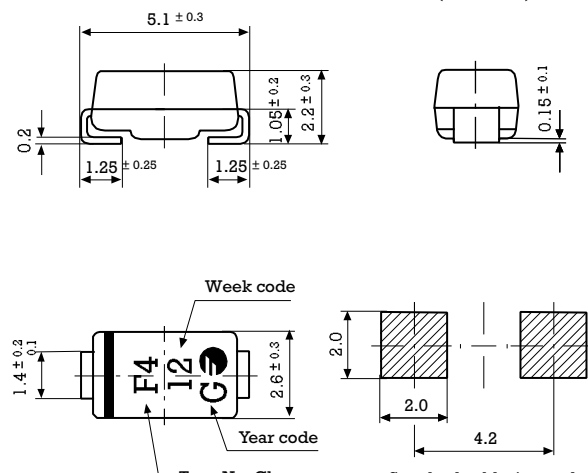


## 1 Amp. Surface Mounted Schottky Barrier Rectifier

Dimensions in mm.	CASE: SMA/DO-214AC (Plastic)	Voltage 20 V to 60 V	Current 1.0 A
 <p>Week code</p> <p>Year code</p> <p>Type No. Closs</p> <p>Standard soldering pad</p>			<ul style="list-style-type: none"> <li>• Metal Silicon Junction, majority carrier conduction</li> <li>• High current capability, low forward voltage drop</li> <li>• Guardring for overvoltage protection</li> <li>• Low power loss, high efficiency</li> <li>• High surge capability</li> <li>• Plastic material carries U/L recognition 94 V0</li> <li>• Low profile package</li> <li>• Easy pick and place</li> </ul>

### Maximum Ratings, according to IEC publication No. 134

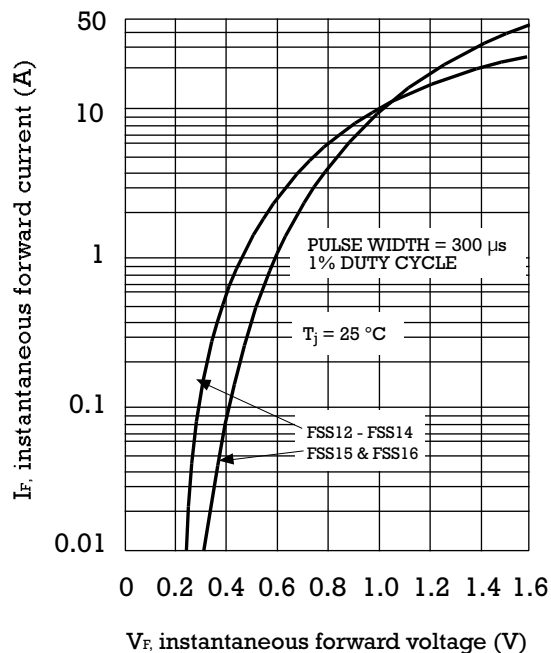
		FSS12	FSS13	FSS14	FSS15	FSS16
Marking Code		A1	A2	A3	A4	A5
V <sub>RRM</sub>	Peak recurrent reverse voltage (V)	20	30	40	50	60
V <sub>RMS</sub>	Maximum RMS voltage (V)	14	21	28	35	42
V <sub>DC</sub>	Maximum DC blocking voltage (V)	20	30	40	50	60
I <sub>F (AV)</sub>	Maximum average Forward current.	1 A				
I <sub>FSM</sub>	8.3 ms. peak forward surge current (Jedec Method)	40 A				
T <sub>j</sub>	Operating temperature range	− 65 to + 125 °C			− 65 to + 150 °C	
T <sub>stg</sub>	Storage temperature range	− 65 to + 150 °C				

### Electrical Characteristics at $T_{amb} = 25\text{ °C}$

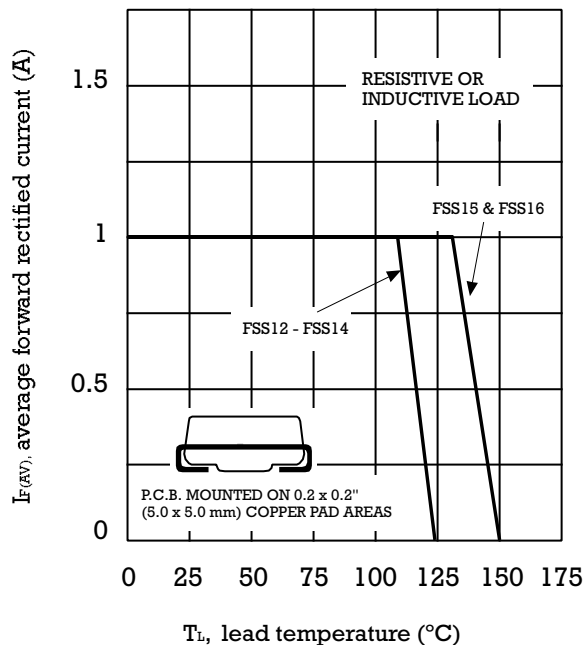
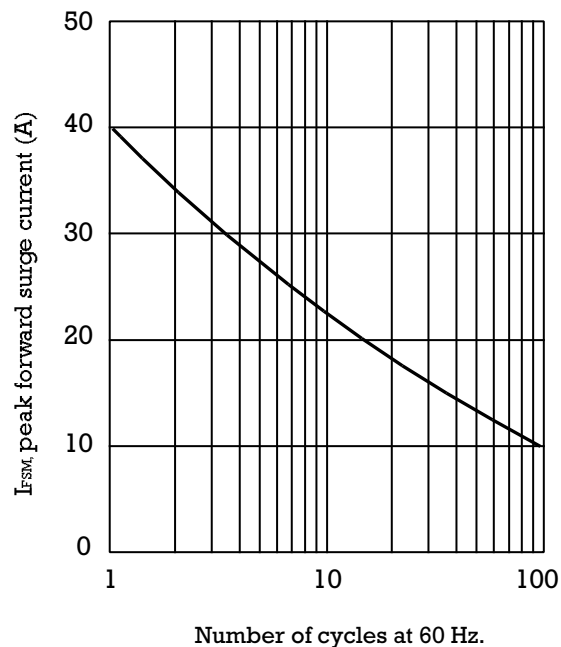
$V_F$	Max. forward voltage drop at $I_F = 1.0\text{ A}$	0.55 V	0.75 V
$I_R$	Max. Instantaneous reverse current at $V_{RRM}$ $T_a = 25\text{ °C}$ $T_a = 100\text{ °C}$	0.5 mA	
		10 mA	5 mA
$R_{thj-a}$ $R_{thj-l}$	Typical Thermal Resistance	88 °C/W 28 °C/W	

NOTE: Thermal Resistance from junction to lead or to ambient PCB mounted with 5x5 mm copper pads areas.

TYPICAL FORWARD CHARACTERISTIC



FORWARD CURRENT DERATING CURVE


MAXIMUM NON-REPETITIVE  
PEAK FORWARD SURGE CURRENT


TYPICAL JUNCTION CAPACITANCE

